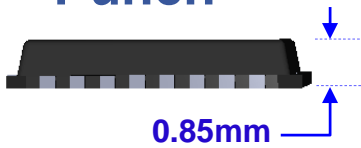

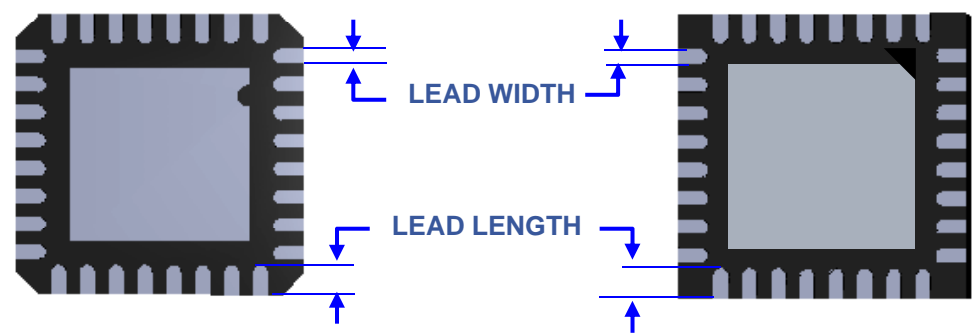


Package Dimensional Differences (Punch versus Sawn)

<p>Punch</p>  <p>0.85mm</p>	<p>Sawn</p>  <p>0.75mm</p>	<p>Package Thickness Difference</p>
 <p>LEAD WIDTH</p> <p>LEAD LENGTH</p>		<p>Aside from Epad dimension, change in Lead Width and Length may affect the Package to PCB solder contact. Maintaining the same dimensions avoids any risk.</p> <p>Bottom Package Pin 1 indicator Change from half Moon to Chamfered Corner</p>

Package Dimensional Differences (Punch versus Sawn)

Body Size (mm)	Lead Count	Punch Type LFCSP Amkor-Korea (AK1)				Sawn Type LFCSP ASE-Korea (AEK)			
		POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)	POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)
4 x 4	16	CP 16-4	2.1 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.30 ± 0.05	CP 16-23	2.1 ± 0.15	0.60 ^{+0.10} _{-0.20}	0.30 ± 0.05
4 x 4	16	CP 16-10	2.35 ± 0.15	0.40 ± 0.10	0.30 ± 0.05	CP 16-24	2.30 ^{+0.15} _{-0.05}	0.40 ± 0.10	0.30 ± 0.05
4 x 4	20	CP 20-1	2.1 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.23 ^{+0.07} _{-0.05}	CP 20-6	2.1 ± 0.10	0.60 ± 0.05	0.25 ^{+0.05} _{-0.07}
4 x 4	24	CP 24-13	2.34 ± 0.10	0.40 ± 0.10	0.23 ^{+0.07} _{-0.05}	CP 24-14	2.34 ± 0.10	0.40 ± 0.10	0.23 ^{+0.07} _{-0.05}
4 x 4	24	CP 24-3	2.5 ± 0.15	0.40 ± 0.10	0.23 ^{+0.07} _{-0.05}	CP 24-7	2.5 ^{+0.15} _{-0.05}	0.40 ± 0.10	0.25 ^{+0.05} _{-0.07}
5 x 5	16	CP 16-6	3.1 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.30 ± 0.05	CP 16-31	3.1 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.30 ± 0.05
5 x 5	32	CP 32-2	3.1 ± 0.15	0.40 ± 0.10	0.23 ^{+0.07} _{-0.05}	CP 32-7	3.1 ± 0.15	0.40 ± 0.10	0.25 ^{+0.05} _{-0.07}
6 x 6	36	CP 36-1	3.7 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.28 ^{+0.07} _{-0.05}	CP 36-4	3.7 ± 0.15	0.60 ^{+0.15} _{-0.10}	0.23 ^{+0.05} _{-0.07}

LEGEND : Tighter (Better)